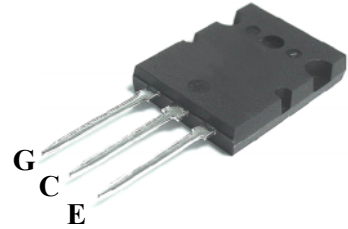
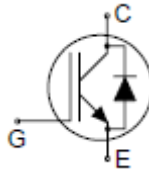


PRELIMINARY DATASHEET
**1200V 75A IGBT with anti-parallel diode,
in TO264 Package**

- Ultra low loss thin IGBT die
- Highly rugged SPT+ design
- Large bondable emitter area


MAXIMUM RATINGS

Parameter	Symbol	Value	Units
Collector-emitter voltage	V_{CE}	1200	V
DC collector current, limited by T_{Jmax} $T_C = 100^\circ\text{C}$	I_C	75	A
Peak collector current	I_{CM}	150	
Diode forward current $T_C = 100^\circ\text{C}$	I_F	60	
Gate-emitter voltage	V_{GE}	± 20	V
Short circuit withstand time ¹ $V_{GE} = 15\text{V}, V_{CC} \leq 400\text{V}, T_J \leq 150^\circ\text{C}$	t_{SC}	10	μs
Operating junction and storage temperature	T_J, T_{stg}	-40... +150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Max. Value	Units
Characteristics			
IGBT thermal resistance, junction to case	R_{thJC}	0.26	K/W
Diode thermal resistance, junction to case	R_{thJCD}	0.4	
Thermal resistance, junction to ambient	R_{thJA}	40	

¹ Allowed number of short circuits: < 1000; time between short circuits: > 1s.

ELECTRICAL CHARACTERISTICS, at $T_J = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0\text{V}, I_C = 1\text{mA}$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15\text{V}, I_C = 75\text{A}$	-	1.8	-	
Diode forward voltage	V_F	$V_{GE} = 0\text{V}, I_F = 60\text{A}$	-	1.85	-	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 3\text{mA}, V_{CE} = V_{GE}$	5.0	6.2	7	
Zero gate voltage collector current	I_{CES}	$V_{CE} = 1200\text{V}, V_{GE} = V_{CE}$	-	-	100	μA
Diode reverse leakage current	I_R	$V_R = 1200\text{V}$	-	-	-	
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}$	-	-	± 200	nA
Integrated gate resistor	R_{Gint}		-	3	-	Ω
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{CE} = 25\text{V},$	-	5520	-	pF
Output capacitance	C_{oss}	$V_{GE} = 0\text{V},$	-	400	-	
Reverse transfer capacitance	C_{rfs}	$f = 1\text{MHz}$	-	260	-	

CAUTION: These devices are ESD sensitive. Use proper handling procedure.

SWITCHING CHARACTERISTICS, Inductive Load at $T_j = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
IGBT Characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{CC}=600\text{V}$, $I_C=75\text{A}$, $V_{GE}=\pm 15\text{V}$, $R_G=15\Omega$, $L_\sigma = 60\text{nH}$, Inductive load.	-	165	-	ns
Rise time	t_r		-	75	-	
Turn-off delay time	$t_{d(off)}$		-	435	-	
Fall time	t_f		-	50	-	
Turn-on energy	E_{on}		-	9.3	-	mJ
Turn-off energy	E_{off}		-	4.5	-	

Anti-Parallel Diode Characteristics

Diode reverse recovery time	t_{rr}	$V_R=600\text{V}$, $I_F=60\text{A}$ $di_F/dt = 1600\text{A}/\mu\text{s}$ $L_\sigma = 60\text{nH}$, Inductive load	-	250	-	ns
Diode reverse recovery charge	Q_{rr}		-	10	-	μC
Diode peak reverse recovery current	I_{rrm}		-	65	-	A

Package Outline Drawing
